BTM852

Bluetooth Module Data Sheet

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Document Version:	V1.0
Release Date:	March 14, 2012

Revision History

Date	Version	Description	Author
2012-03-14	V1.0	■ First Release	

CONTENT

1. INTRODUCTION

The BTM852 bluetooth module is a perfect solution for Bluetooth Application, depends on host profile application, it can realize distribution of audio, transfer of file & picture, control of remote device, and so on. It can be connected with any bluetooth devices in an operating range. It is slim and light so the designers can have better flexibilities for the product shapes.

The BTM852 bluetooth module compile with blue tooth specification version 4.0. It integrates RF, Baseband controller, antenna matching, etc and provide USB interface, programmable I/O, PCM etc.

The detail information of BTM852 blue tooth module is presented in this document below.

1.1 Block Diagram

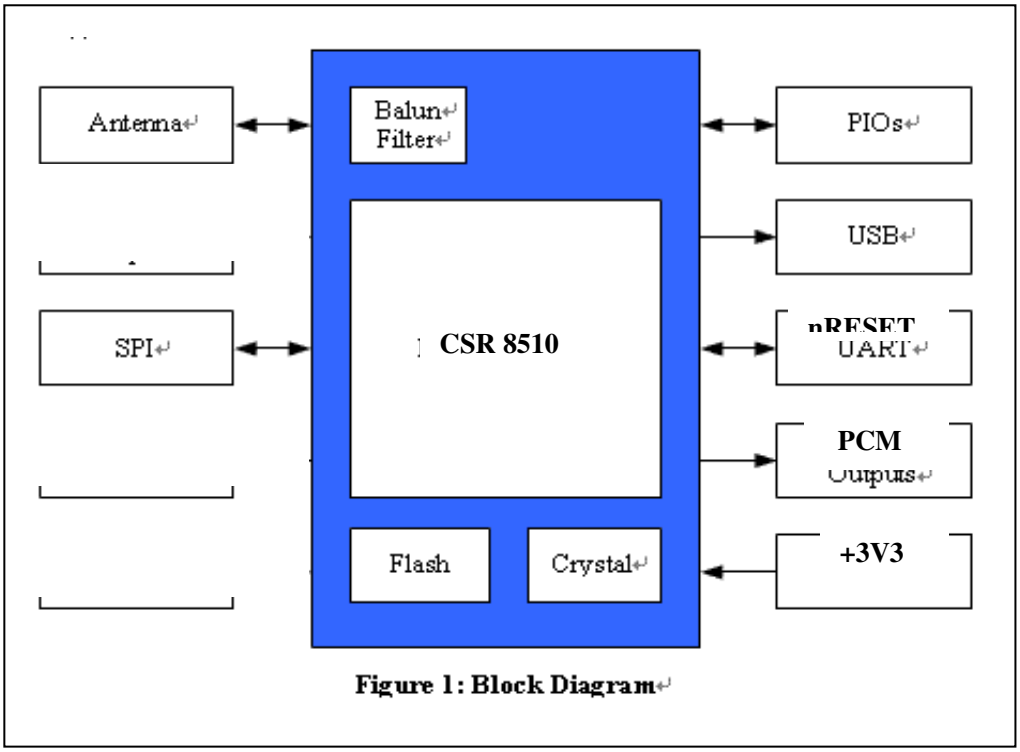


Figure 1: Block Diagram

1.2 Features

- ✓ Small overall dimension(30mm x 14.5mm x 2mm)
- ✓ Bluetooth Specification V4.0
- ✓ Class 2 and Class 3 support
- ✓ Physical connection as SMD type
- ✓ Built-in RF combo filter, Integrated 26M Crystal.
- ✓ Support profile by Host.
- ✓ No radio signal interference, support for 802.11 co-existence

※ ***Some features are optional for customization on demand.***

1.3 Application

- ✓ TV Set-top Boxes and Smart TV
- ✓ Notebooks ane Desktops
- ✓ USB Bluetooth Dongle
- ✓ Bluetooth Low Energy

2. GENERAL SPECIFICATION

Bluetooth Specification	
Chip Set	CSR 8510
Module ID	BTM852
BT Standard	Bluetooth® V4.0
RF TX Output Power	4dBm (Class II)
Sensitivity	-86dBm@0.1%BER
Frequency Band	2.402GHz~2.480GHz ISM Band
Baseband Crystal OSC	26MHz
Hopping	1600hops/sec, 1MHz channel space
RF Input Impedance	50 ohms
Major Interface	• PCM : Output • USB : DP/DN • PIOs • Antenna
Profile	Support Profile by Host
Power	
Supply Voltage	3.0V ~ 3.6V DC or 5.0V ~ 5.5V (Optional)
Working Current	35mA typical, Depends on profiles
Standby Current	<1mA
Operating Environment	
Temperature	-40ºC to +85ºC
Humidity	10%~90% Non-Condensing
Environmental	RoHS Compliant

3. PHYSICAL CHARACTERISTIC

Dimension:

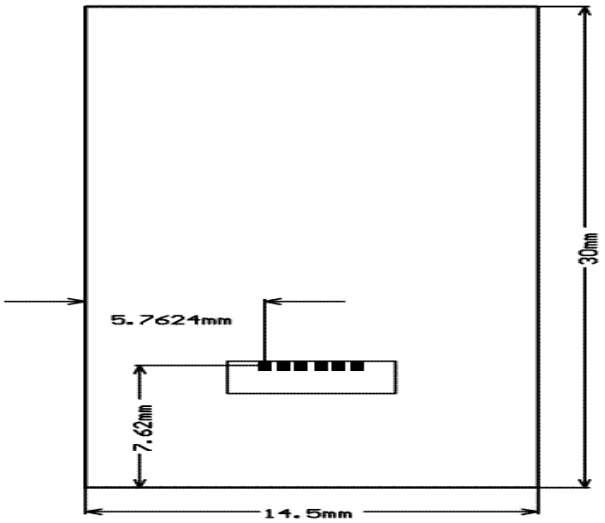


Figure 2

Top View:

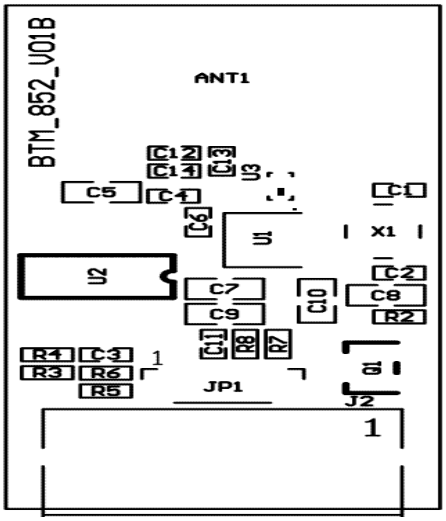


Figure 3

Pin Definition:

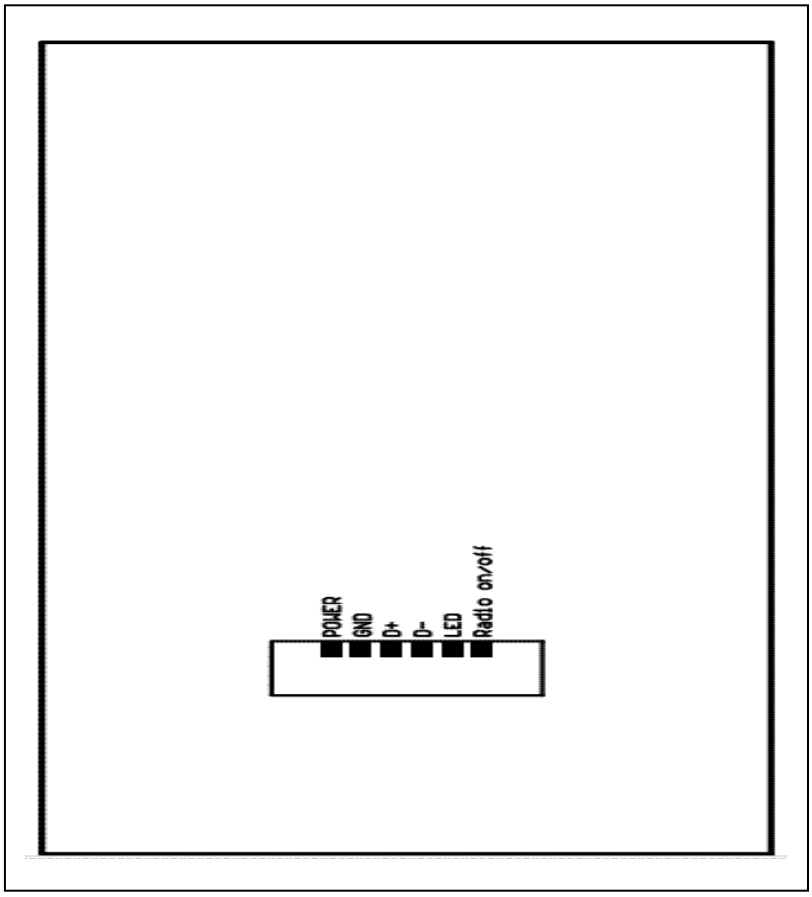


Figure 4

3.1 Pin Description

Pin#	Pin Name	Pad Type	Description
1	POWER	Power Supply	Positive supply for BT Module(5.0V~5.5V)
2	GND	Ground	Digital Ground
3	D+	Bi-directional	USB data plus with selectable internal 1.5kΩ pull-up resistor
4	D-	Bi-directional	USB data minus
5	LED	Open drain output	BT Module State Indication (Optional)
6	Radio ON/OFF	RF	BT Radio ON/OFF (Optional)

4. REFERENCE SCHEMATIC

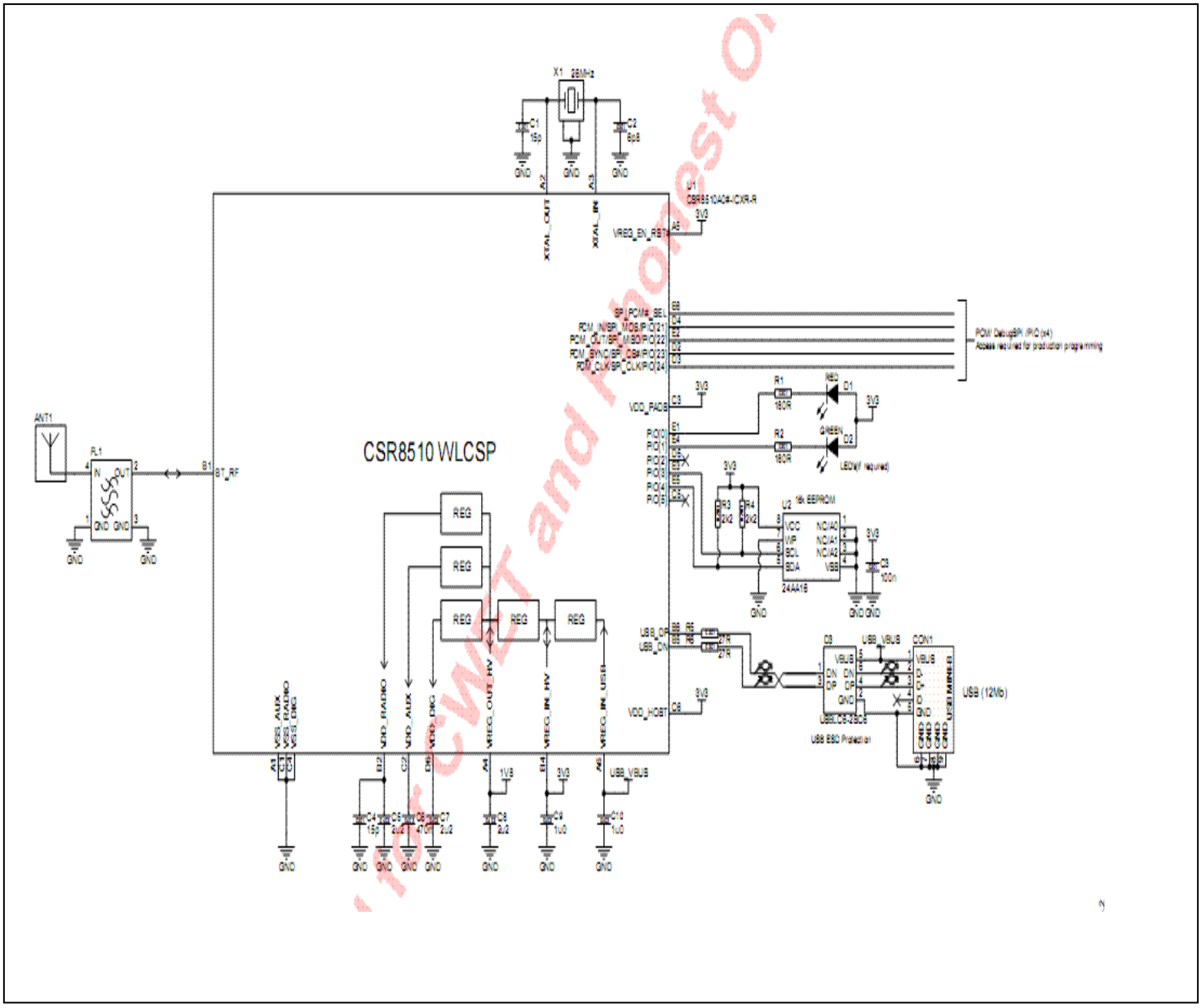


Figure 5

5. PHYSICAL INTERFACE

5.1 Power Supply

The transient response of the regulator is important. If the power rails of the module are supplied from an external voltage source, the transient response of any regulator used should be 20μs or less.

5.2 RF Interface

The module integrates a balun filter. The user can connect a 50ohms antenna directly to the RF port. The module integrates PCB antenna.

5.3 Serial Interfaces

5.3.1 USB

There is a full speed (12M bits/s) USB interface for communicating with other compatible digital devices. The module acts as a USB peripheral, responding to request from a master host controller, such as a PC.

The module features an internal USB pull-up resistor. This pulls the USB_DP pin weakly high when module is ready to enumerate. It signals to the USB master that it is a full speed (12Mbit/s) USB device. The USB internal pull-up is implemented as a current source, and is compliant with section7.1.5 of the USB specification v1.2. The internal pull-up pulls USB_DP high to at least 2.8V when loaded with a 15kΩ ±5% pull-down resistor (in the hub/host) when VDD =3.1V. This presents a The venin resistance to the host of at least 900Ω. Alternatively, an external 1.5kΩ pull-up resistor can be placed between a PIO line and DP on the USB cable.

5.3.2 SPI

The synchronous serial port interface (SPI) can be used for system debugging. It can also be used for in-system programming for the flash memory within the module. SPI interface uses the SPI_MOSI, SPI_MISO, SPI_CSB and SPI_CLK pins. Testing points for the SPI interface are reserved on board in case that the firmware shall be updated during manufacture.

The module operates as a slave and thus SPI_MISO is an output of the module. SPI_MISO is not in high-impedance state when SPI_CSB is pulled high. Instead, the module outputs 0 if the processor is running and 1 if it is stopped. Thus the module should NOT be connected in a multi-slave arrangement by simple parallel connection of slave SPI_MISO lines.

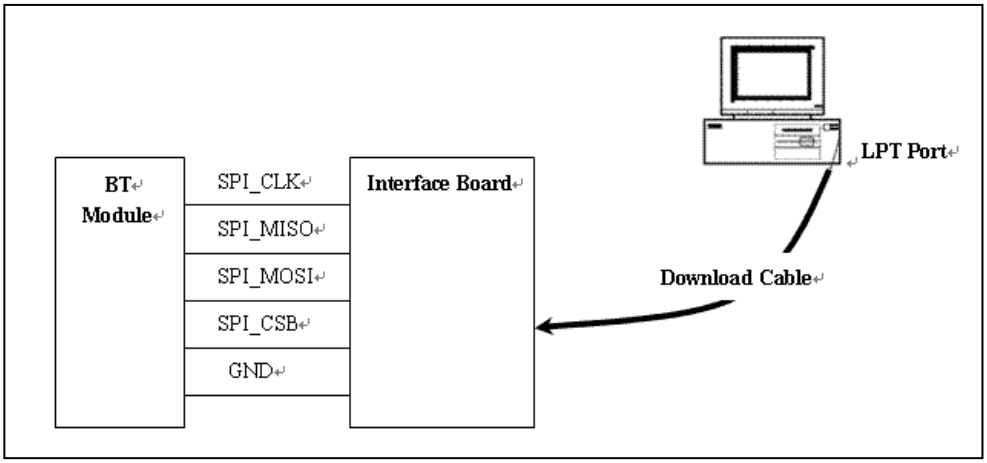


Figure 6

6. ELECTRICAL CHARACTERISTIC

6.1 Absolute Maximum Rating

Rating	Min	Max	Unit
Storage Temperature	-40	+150	°C
Operating Temperature	-40	+105	°C
PIO/AIO Voltage	-0.4	+3.6	V
+5V Voltage	-0.4	+5.5	V
USB_DP/USB_DN Voltage	-0.4	+5.5	V
Other Terminal Voltages except RF	-0.4	5V+0.4	V

Table 1

6.2 Recommended Operating Conditions

Operating Condition	Min	Typical	Max	Unit
Operating Temperature Range	-40	--	+85	°C
+5V Voltage	+5.0	+5.0	+5.5	V

Table 2

6.3 Input/output Terminal Characteristics

6.3.1 Digital Terminals

Supply Voltage Levels	Min	Typical	Max	Unit
Input Voltage Levels				
VIL input logic level low	-0.3	-	+0.25x5V	V
VIH input logic level high	0.625*5V	-	5V+0.3	V
Output Voltage Levels				
V_{OL} output logic level low, I_{OL} = 4.0mA	-	-	0.125	V
V_{OH} output logic level high, I_{OH} = -4.0mA	0.75x5V	-	0.625x5V	V
Input and Tri-state Current				
Ii input leakage current at Vin=+3V3 or 0V	-100	0	100	nA
Ioz tri-state output leakage current at Vo=+3V3 or 0V	-100	0	100	nA
With strong pull-up	-100	-40	-10	µA
With strong pull-down	10	40	100	µA
With weak pull-up	-5	-1.0	-0.2	µA
With weak pull-down	0.2	+1.0	5.0	µA
I/O pad leakage current	-1	0	+1	µA

CI Input Capacitance	1.0	-	5.0	pF
Resistive Strength				
Rpuw weak pull-up strength at +3V3-0.2V	500k	-	2M	Ω
Rpdw weak pull-up strength at 0.2V	500k	-	2M	Ω
Rpus strong pull-up strength at +3V3-0.2V	10k	-	50k	Ω
Rpds strong pull-up strength at 0.2V	10k	-	50k	Ω

Table 3

6.3.2 USB

USB Terminals	Min	Typical	Max	Unit
Input Threshold				
V_{IL} input logic level low	-	-	0.3*3V3	V
V_{IH} input logic level high	0.7*3V3	-	-	V
Input Leakage Current				
GND < VIN < +3V3[(a)]	-1	1	5	µA
CI Input capacitance	2.5	-	10.0	pF
Output Voltage Levels to Correctly Terminated USB Cable				
V_{IL} output logic level low	0.0	-	0.2	V
V_{IH} output logic level high	2.8	-	+3V3	V

Table 4

6.4 Power consumptions

Operating Condition	Min	Typical	Max	Unit
Connected Idle (Sniff 1.28 secs)		0.19		mA
Connected with audio streaming	30	35	40	mA
Deep Sleep Idle mode		60		µA

Table 5

7. RECOMMENDED TEMPERATURE REFLOW PROFILE

The soldering profile depends on various parameters necessitating a set up for each application. The data here is given only for guidance on solder reflow.

2F Friday March 09, 2012 10:21:21

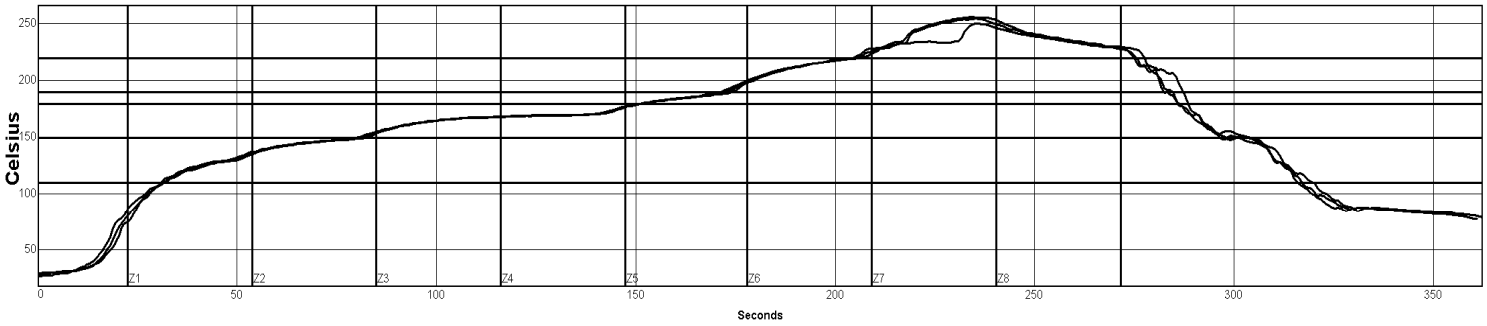
Site:

Oven Name: WQ Process Window Name: 无铅

Setpoints (Celsius)

Zone	1	2	3	4	5	6	7	8
Top	140	150	170	170	190	225	265	230
Bottom	140	150	170	170	190	225	265	230

Conveyor Speed (cm/min): 75.0



PWI= 304%	Max Rising Slope		Preheat 110-190C		Soak Time 150-180C		Reflow Time /220C		Peak Temp	
2	3.9	189%	141.4	157%	70.4	-296%	71.1	111%	254.8	97%
3	4.0	197%	139.7	149%	70.6	-294%	70.3	103%	250.6	11%
4	3.9	192%	142.1	160%	69.6	-304%	71.2	112%	256.5	130%

Process Window:

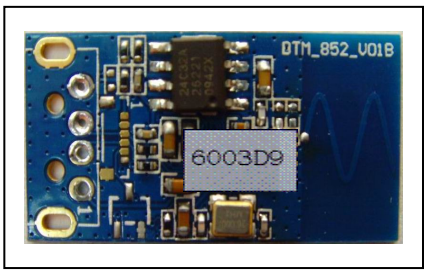
Solder Paste: SYSTEM DEFAULT

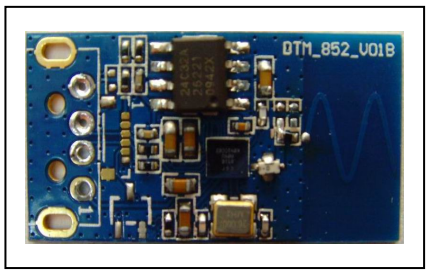
Statistic Name	Low Limit	High Limit	Units
Max Rising Slope (Target=2.0)	0.0	3.0	Degrees/Second
Preheat Time 110-190C	90	130	Seconds
Soak Time 150-180C	90	110	Seconds
Time Above Reflow - 220C	50	70	Seconds
Peak Temperature	245	255	Degrees Celsius

Description:

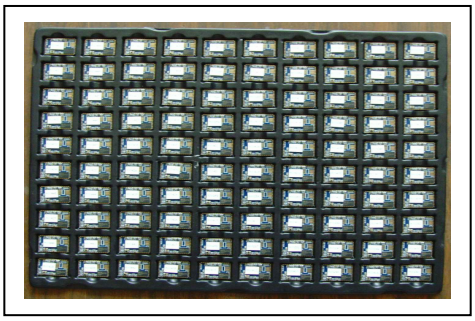
8. PACKAGING INFORMATION

1. BLUETOOTH® Module: BTM852





2. Assembly



3. Dimension